

PCN Number:	20190628000.1		PCN Date:	July 8, 2019													
Title:	Qualification of TI Clark as an Assembly site for Select Devices																
Customer Contact:	PCN Manager	Dept:	Quality Services														
Proposed 1st Ship Date:	Sept 28 2019	Estimated Sample Availability:	Date provided at sample request														
Change Type:																	
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site												
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material												
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process												
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site												
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials												
		<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process												
PCN Details																	
Description of Change:																	
Texas Instruments is pleased to announce the qualification of TI Clark as an Additional Assembly site for the list of devices shown below. Current assembly sites and Material differences are as follows:																	
<table border="1"> <thead> <tr> <th></th> <th>UTAC</th> <th>TI Clark</th> </tr> </thead> <tbody> <tr> <td>Mount Compound (Bottom)</td> <td>SID#PZ0035</td> <td>4207123</td> </tr> <tr> <td>Mount Compound (Top)</td> <td>SID#PZ0076</td> <td>4221460</td> </tr> <tr> <td>Lead Finish</td> <td>NiPdAuAg</td> <td>NiPdAu</td> </tr> </tbody> </table>							UTAC	TI Clark	Mount Compound (Bottom)	SID#PZ0035	4207123	Mount Compound (Top)	SID#PZ0076	4221460	Lead Finish	NiPdAuAg	NiPdAu
	UTAC	TI Clark															
Mount Compound (Bottom)	SID#PZ0035	4207123															
Mount Compound (Top)	SID#PZ0076	4221460															
Lead Finish	NiPdAuAg	NiPdAu															
Reason for Change:																	
Continuity of Supply																	
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																	
None																	
Anticipated impact on Material Declaration																	
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp														
Changes to product identification resulting from this PCN:																	
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City														
UTAC	NSE	THA	Bangkok														
TI Clark	QAB	PHL	Angeles City, Pampanga														
Sample product shipping label (not actual product label)																	



MADE IN: Malaysia
2DC: 20:

MSL '2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM:

LBL: 5A (L)T0:1750



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO: USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

CC3220SF12ARGKR	CC3220SF12ARGKT	CC3235SF12RGKR
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TI Information
Selective Disclosure

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: CC3220SF12RGK	QBS Product Reference: CC3XXX	QBS Package Reference: 430FR5969IRGZR
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	-
HBM	ESD HBM	2000 V	-	1/3/0	-
CDM	ESD CDM	500V	-	1/3/0	-
EDR+ HTOL	Life Test, 125C – 100K W/E Endurance cycles followed by 1000 hours HTOL	1000 Hours	-	2/148/0	-
EDR+ HTSL	High Temp. Storage Bake, 150C– 100K W/E Endurance cycles followed by 1000 hours HTSL	1000 Hours	-	3/230/0	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	-	3/229/0
LU	Latchup	(per JESD78)	-	1/6/0	-
MQ	TEST MQ	-	Pass	Pass	Pass
TC	Temperature Cycle, -55/125C	700 Cycles	3/231/0	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	3/231/0
THB	Biased Temperature & Humidity, 85C/85%RH	1000 Hours	3/77/0	3/77/0	-
BHAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0
UHAST	Unbiased HAST, 110C/85%RH	264 Hours	3/230/0	3/231/0	-
AC	Autoclave 121C	96 Hours	-	-	3/231/0

- QBS: Qual By Similarity
- Qual Device CC3220SF12RGK is qualified at LEVEL3-260CG
- Device CC3220SF12RGK contains multiple dies.
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com